L Number	Hits	Search Text	DB	Time stamp
1	2234	(257/59,72).ccls.	USPAT;	2004/08/14 13:15
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
2	3014	(349/42,43,187).ccls.	USPAT;	2004/08/14 13:16
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
_	21.000	th award 10 to a 10 (th award 10 to a	IBM_TDB	2004/00/14 12:16
3	31889	thermal\$3-treat\$3 (thermal\$3 near5 treat\$3) thermal\$3 adj	USPAT; US-PGPUB;	2004/08/14 13:16
		treat\$3	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
4	26262	(alignment aliging orientation orienting) adj (layer film)	USPAT;	2004/08/14 13:17
'	20202	(ungrament unging offertation offertally) auf (unjer min)	US-PGPUB;	200 1/00/21 2012/
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
5	1607944	simultaneous\$3	USPAT;	2004/08/14 13:17
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
6	2	(thermal\$3-treat\$3 (thermal\$3 near5 treat\$3) thermal\$3 adj	USPAT;	2004/08/14 13:19
		treat\$3) same ((alignment aliging orientation orienting) adj (layer	US-PGPUB;	
		film)) same simultaneous\$3 -	EPO; JPO;	
			DERWENT;	
-	55667	(accordingly) and all advanta	IBM_TDB	2004/00/14 12:10
7	55667	(source drain) adj electrode	USPAT;	2004/08/14 13:19
			US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM_TDB	
8	224005	heat\$3 adj treatment	USPAT;	2004/08/14 13:20
	22 1003	Troutes day deathful	US-PGPUB;	2001/00/1115.20
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
9	3843575	heat\$3	USPAT;	2004/08/14 13:20
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
10	1722742	a	IBM_TDB	2004/00/44 42:22
10	1722712	cur\$3	USPAT;	2004/08/14 13:20
			US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM_TDB	
11	4999721	heat\$3 cur\$3 (heat\$3 adj treatment) (thermal\$3-treat\$3	USPAT;	2004/08/14 13:21
**	1,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	(thermal\$3 near5 treat\$3) thermal\$3 adj treat\$3)	US-PGPUB;	500 1/00/14 12:51
		(a.aa.go modeo) anomalyo day a cacyo)	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
12	1	(heat\$3 cur\$3 (heat\$3 adj treatment) (thermal\$3-treat\$3	USPAT;	2004/08/14 13:22
		(thermal\$3 near5 treat\$3) thermal\$3 adj treat\$3)) near10	US-PGPUB;	
		((alignment aliging orientation orienting) adj (layer film)) near10	EPO; JPO;	
		((source drain) adj electrode)	DERWENT;	
L			IBM_TDB	

13-	25	(heat\$3 cur\$3 (heat\$3 adj treatment) (thermal\$3-treat\$3 (thermal\$3 near5 treat\$3) thermal\$3 adj treat\$3)) same ((alignment aliging orientation orienting) adj (layer film)) same	USPAT; US-PGPUB; EPO; JPO;	2004/08/14 13:23
		((source drain) adj electrode)	DERWENT; IBM_TDB	
15	8	((349/42,43,187).ccls.) and ((heat\$3 cur\$3 (heat\$3 adj treatment) (thermal\$3-treat\$3 (thermal\$3 near5 treat\$3) thermal\$3 adj	USPAT; US-PGPUB;	2004/08/14 13:23
		treat\$3)) same ((alignment aliging orientation orienting) adj (layer film)) same ((source drain) adj electrode))	EPO; JPO; DERWENT; IBM_TDB	
14	3	((257/59,72).ccls.) and ((heat\$3 cur\$3 (heat\$3 adj treatment) (thermal\$3-treat\$3 (thermal\$3 near5 treat\$3) thermal\$3 adj	USPAT; US-PGPUB;	2004/08/14 13:24
:		treat\$3)) same ((alignment aliging orientation orienting) adj (layer film)) same ((source drain) adj electrode))	EPO; JPO; DERWENT; IBM_TDB	
16	135025	(active semiconductor) adj (layer film)	USPAT; US-PGPUB;	2004/08/14 13:25
			EPO; JPO; DERWENT; IBM_TDB	
17	56991	ohmic	USPAT; US-PGPUB;	2004/08/14 13:25
			EPO; JPO; DERWENT; IBM_TDB	
18	1524167	pattern\$3	USPAT; US-PGPUB;	2004/08/14 13:25
			EPO; JPO; DERWENT; IBM_TDB	
19	436865	mask	USPAT; US-PGPUB;	2004/08/14 13:25
1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1			EPO; JPO; DERWENT; IBM_TDB	
20	121	((active semiconductor) adj (layer film)) near10 ohmic near10 pattern\$3 near10 mask	USPAT; US-PGPUB;	2004/08/14 13:26
			EPO; JPO; DERWENT; IBM_TDB	
21	16	simultaneous\$3 near10 (((active semiconductor) adj (layer film)) near10 ohmic near10 pattern\$3 near10 mask)	USPAT; US-PGPUB;	2004/08/14 13:29
			EPO; JPO; DERWENT; IBM_TDB	
22	1	simultaneous\$3 near10 ((source drain) adj electrode) near10 ((alignment aliging orientation orienting) adj (layer film))	USPAT; US-PGPUB;	2004/08/14 13:30
			EPO; JPO; DERWENT; IBM_TDB	
23	81420	simultaneous\$3 near10 (heat\$3 cur\$3 (heat\$3 adj treatment) (thermal\$3-treat\$3 (thermal\$3 near5 treat\$3) thermal\$3 adj	USPAT; US-PGPUB;	2004/08/14 13:31
		treat\$3))	EPO; JPO; DERWENT; IBM_TDB	
25	0	((simultaneous\$3 near10 (heat\$3 cur\$3 (heat\$3 adj treatment) (thermal\$3-treat\$3 (thermal\$3 near5 treat\$3) thermal\$3 adj	USPAT; US-PGPUB;	2004/08/14 13:31
		treat\$3))) near10 ((alignment aliging orientation orienting) adj (layer film))) near10 ((source drain) adj electrode)	EPO; JPO; DERWENT; IBM_TDB	

24	22	(,	USPAT;	2004/08/14 13:33
		(thermal\$3-treat\$3 (thermal\$3 near5 treat\$3) thermal\$3 adj	US-PGPUB;	
		treat\$3))) near10 ((alignment aliging orientation orienting) adj	EPO; JPO;	
		(layer film))	DERWENT;	
			IBM_TDB	
26	152939	annealing	USPAT;	2004/08/14 13:34
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
27	1	simultaneous\$3 near10 (heat\$3 cur\$3 (heat\$3 adj treatment)	USPAT;	2004/08/14 13:34
		(thermal\$3-treat\$3 (thermal\$3 near5 treat\$3) thermal\$3 adj	US-PGPUB;	
		treat\$3)) near10 ((alignment aliging orientation orienting) adj	EPO; JPO;	
		(layer film)) near10 annealing	DERWENT;	
			IBM_TDB	
28	2	simultaneous\$3 same (heat\$3 cur\$3 (heat\$3 adj treatment)	USPAT;	2004/08/14 13:35
		(thermal\$3-treat\$3 (thermal\$3 near5 treat\$3) thermal\$3 adj	US-PGPUB;	
		treat\$3)) same ((alignment aliging orientation orienting) adj (layer	EPO; JPO;	
		film)) same annealing	DERWENT;	
			IBM_TDB	